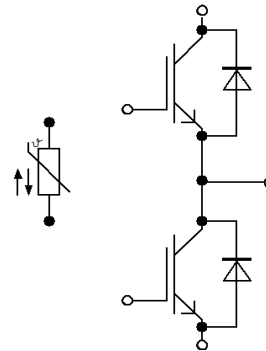
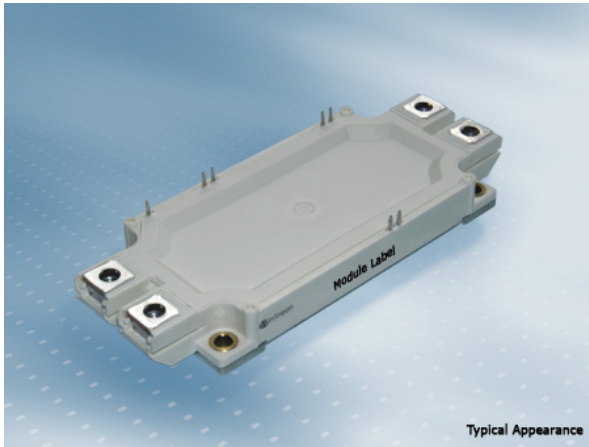


EconoDUAL™3 Modul mit schnellem Trench/Feldstopp IGBT4 und Emitter Controlled Diode und NTC
 EconoDUAL™3 module with fast Trench/Fieldstop IGBT4 and Emitter Controlled diode and NTC



$V_{CES} = 650V$
 $I_{C\ nom} = 450A / I_{CRM} = 900A$

Potentielle Anwendungen

- Hybrid-Nutzfahrzeuge
- Motorantriebe
- Solar Anwendungen
- USV-Systeme

Potential Applications

- Commercial Agriculture Vehicles
- Motor drives
- Solar applications
- UPS systems

Elektrische Eigenschaften

- Erhöhte Sperrspannungsfestigkeit auf 650V
- Erhöhte Zwischenkreisspannung
- Hohe Kurzschlussrobustheit
- Hohe Stoßstromfestigkeit
- Hohe Stromdichte
- $T_{vj\ op} = 150^{\circ}C$
- Trench IGBT 4

Electrical Features

- Increased blocking voltage capability up to 650V
- Increased DC-link voltage
- High short-circuit capability
- High surge current capability
- High current density
- $T_{vj\ op} = 150^{\circ}C$
- Trench IGBT 4

Mechanische Eigenschaften

- Hohe Leistungsdichte
- Integrierter NTC Temperatur Sensor
- Isolierte Bodenplatte
- Kupferbodenplatte
- Standardgehäuse

Mechanical Features

- High power density
- Integrated NTC temperature sensor
- Isolated base plate
- Copper base plate
- Standard housing

Module Label Code

Barcode Code 128



DMX - Code



Content of the Code

Content of the Code	Digit
Module Serial Number	1 - 5
Module Material Number	6 - 11
Production Order Number	12 - 19
Datecode (Production Year)	20 - 21
Datecode (Production Week)	22 - 23

IGBT, Wechselrichter / IGBT, Inverter

Höchstzulässige Werte / Maximum Rated Values

Kollektor-Emitter-Sperrspannung Collector-emitter voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{CES}	650	V
Kollektor-Dauergleichstrom Continuous DC collector current	$T_C = 70^{\circ}\text{C}, T_{vj\text{ max}} = 175^{\circ}\text{C}$	I_{CDC}	450	A
Periodischer Kollektor-Spitzenstrom Repetitive peak collector current	$t_P = 1\text{ ms}$	I_{CRM}	900	A
Gate-Emitter-Spitzenspannung Gate-emitter peak voltage		V_{GES}	+/-20	V

Charakteristische Werte / Characteristic Values

			min.	typ.	max.		
Kollektor-Emitter-Sättigungsspannung Collector-emitter saturation voltage	$I_C = 450\text{ A}$ $V_{GE} = 15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_{CE\text{ sat}}$	1,55 1,70 1,75	1,95	V V V	
Gate-Schwellenspannung Gate threshold voltage	$I_C = 7,20\text{ mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$		V_{GEth}	5,10	5,80	6,40	V
Gateladung Gate charge	$V_{GE} = -15 / 15\text{ V}$		Q_G	4,80			μC
Interner Gatewiderstand Internal gate resistor	$T_{vj} = 25^{\circ}\text{C}$		R_{Gint}	0,67			Ω
Eingangskapazität Input capacitance	$f = 1000\text{ kHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		C_{ies}	27,5			nF
Rückwirkungskapazität Reverse transfer capacitance	$f = 1000\text{ kHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		C_{res}	0,82			nF
Kollektor-Emitter-Reststrom Collector-emitter cut-off current	$V_{CE} = 650\text{ V}, V_{GE} = 0\text{ V}, T_{vj} = 25^{\circ}\text{C}$		I_{CES}			1,0	mA
Gate-Emitter-Reststrom Gate-emitter leakage current	$V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V}, T_{vj} = 25^{\circ}\text{C}$		I_{GES}			100	nA
Einschaltverzögerungszeit, induktive Last Turn-on delay time, inductive load	$I_C = 450\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{Gon} = 1,8\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_{don}	0,085 0,089 0,093			μs μs μs
Anstiegszeit, induktive Last Rise time, inductive load	$I_C = 450\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{Gon} = 1,8\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_r	0,082 0,087 0,088			μs μs μs
Abschaltverzögerungszeit, induktive Last Turn-off delay time, inductive load	$I_C = 450\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{Goff} = 1,8\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_{doff}	0,48 0,51 0,52			μs μs μs
Fallzeit, induktive Last Fall time, inductive load	$I_C = 450\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{Goff} = 1,8\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_f	0,067 0,093 0,099			μs μs μs
Einschaltverlustenergie pro Puls Turn-on energy loss per pulse	$I_C = 450\text{ A}, V_{CE} = 300\text{ V}, L\sigma = 30\text{ nH}$ $di/dt = 4900\text{ A}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $V_{GE} = -15 / 15\text{ V}, R_{Gon} = 1,8\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{on}	3,40 4,60 4,90			mJ mJ mJ
Abschaltverlustenergie pro Puls Turn-off energy loss per pulse	$I_C = 450\text{ A}, V_{CE} = 300\text{ V}, L\sigma = 30\text{ nH}$ $du/dt = 2600\text{ V}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $V_{GE} = -15 / 15\text{ V}, R_{Goff} = 1,8\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{off}	23,5 28,5 30,0			mJ mJ mJ
Kurzschlußverhalten SC data	$V_{GE} \leq 15\text{ V}, V_{CC} = 360\text{ V}$ $V_{CEmax} = V_{CES} - L_{SCE} \cdot di/dt$ $t_P \leq 10\ \mu\text{s}, T_{vj} = 150^{\circ}\text{C}$		I_{SC}	2400			A
Wärmewiderstand, Chip bis Gehäuse Thermal resistance, junction to case	pro IGBT / per IGBT		R_{thJC}			0,102	K/W
Wärmewiderstand, Gehäuse bis Kühlkörper Thermal resistance, case to heatsink	pro IGBT / per IGBT $\lambda_{Paste} = 1\text{ W}/(\text{m}\cdot\text{K})$ / $\lambda_{grease} = 1\text{ W}/(\text{m}\cdot\text{K})$		R_{thCH}			0,0390	K/W
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj\text{ op}}$	-40		150	$^{\circ}\text{C}$

Diode, Wechselrichter / Diode, Inverter

Höchstzulässige Werte / Maximum Rated Values

Periodische Spitzensperrspannung Repetitive peak reverse voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{RRM}	650	V
Dauergleichstrom Continuous DC forward current		I_F	450	A
Periodischer Spitzenstrom Repetitive peak forward current	$t_P = 1\text{ ms}$	I_{FRM}	900	A
Grenzlastintegral I^2t - value	$V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 125^{\circ}\text{C}$ $V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 150^{\circ}\text{C}$	I^2t	15000 14500	A^2s A^2s

Charakteristische Werte / Characteristic Values

		min.	typ.	max.	
Durchlassspannung Forward voltage	$I_F = 450\text{ A}, V_{GE} = 0\text{ V}$ $T_{vj} = 25^{\circ}\text{C}$		1,55	1,95	V
	$I_F = 450\text{ A}, V_{GE} = 0\text{ V}$ $T_{vj} = 125^{\circ}\text{C}$		1,50		V
	$I_F = 450\text{ A}, V_{GE} = 0\text{ V}$ $T_{vj} = 150^{\circ}\text{C}$		1,45		V
Rückstromspitze Peak reverse recovery current	$I_F = 450\text{ A}, -di_F/dt = 4900\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $T_{vj} = 25^{\circ}\text{C}$		185		A
	$V_R = 300\text{ V}$ $T_{vj} = 125^{\circ}\text{C}$		270		A
	$V_{GE} = -15\text{ V}$ $T_{vj} = 150^{\circ}\text{C}$		285		A
Sperrverzögerungsladung Recovered charge	$I_F = 450\text{ A}, -di_F/dt = 4900\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $T_{vj} = 25^{\circ}\text{C}$		26,5		μC
	$V_R = 300\text{ V}$ $T_{vj} = 125^{\circ}\text{C}$		30,0		μC
	$V_{GE} = -15\text{ V}$ $T_{vj} = 150^{\circ}\text{C}$		35,5		μC
Abschaltenergie pro Puls Reverse recovery energy	$I_F = 450\text{ A}, -di_F/dt = 4900\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $T_{vj} = 25^{\circ}\text{C}$		5,90		mJ
	$V_R = 300\text{ V}$ $T_{vj} = 125^{\circ}\text{C}$		8,90		mJ
	$V_{GE} = -15\text{ V}$ $T_{vj} = 150^{\circ}\text{C}$		10,5		mJ
Wärmewiderstand, Chip bis Gehäuse Thermal resistance, junction to case	pro Diode / per diode	R_{thJC}		0,165	K/W
Wärmewiderstand, Gehäuse bis Kühlkörper Thermal resistance, case to heatsink	pro Diode / per diode $\lambda_{Paste} = 1\text{ W}/(\text{m}\cdot\text{K}) / \lambda_{grease} = 1\text{ W}/(\text{m}\cdot\text{K})$	R_{thCH}	0,0400		K/W
Temperatur im Schaltbetrieb Temperature under switching conditions		$T_{vj\text{ op}}$	-40	150	$^{\circ}\text{C}$

NTC-Widerstand / NTC-Thermistor

Charakteristische Werte / Characteristic Values

		min.	typ.	max.	
Nennwiderstand Rated resistance	$T_{NTC} = 25^{\circ}\text{C}$	R_{25}	5,00		$\text{k}\Omega$
Abweichung von R100 Deviation of R100	$T_{NTC} = 100^{\circ}\text{C}, R_{100} = 493\ \Omega$	$\Delta R/R$	-5	5	%
Verlustleistung Power dissipation	$T_{NTC} = 25^{\circ}\text{C}$	P_{25}		20,0	mW
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298,15\text{ K}))]$	$B_{25/50}$	3375		K
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/80}(1/T_2 - 1/(298,15\text{ K}))]$	$B_{25/80}$	3411		K
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/100}(1/T_2 - 1/(298,15\text{ K}))]$	$B_{25/100}$	3433		K

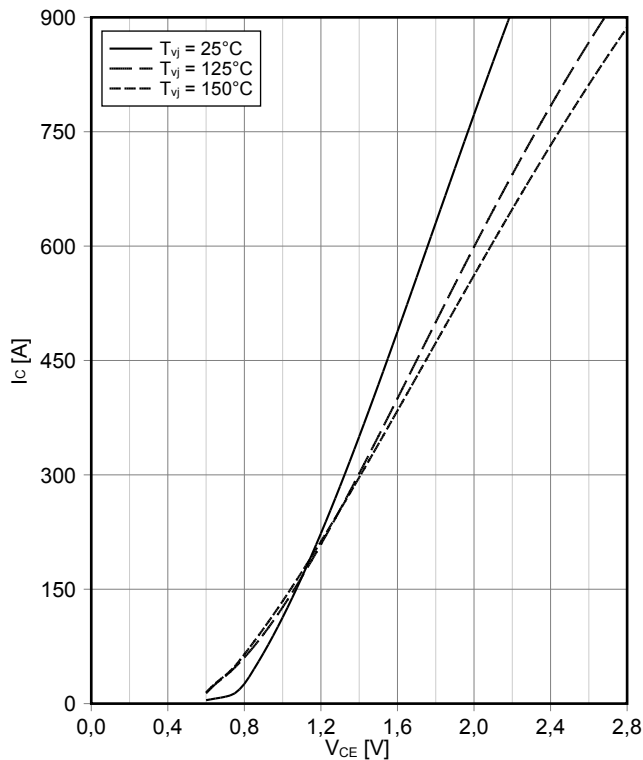
Angaben gemäß gültiger Application Note.
Specification according to the valid application note.

Modul / Module

Isolations-Prüfspannung Isolation test voltage	RMS, f = 50 Hz, t = 1 min.	V _{ISOL}	2,5		kV
Material Modulgrundplatte Material of module baseplate			Cu		
Innere Isolation Internal isolation	Basisisolierung (Schutzklasse 1, EN61140) basic insulation (class 1, IEC 61140)		Al ₂ O ₃		
Kriechstrecke Creepage distance	Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal		14,5 13,0		mm
Luftstrecke Clearance	Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal		12,5 10,0		mm
Vergleichszahl der Kriechwegbildung Comperative tracking index		CTI	> 200		
			min.	typ.	max.
Modulstreuintuktivität Stray inductance module		L _{sCE}		20	nH
Modulleitungswiderstand, Anschlüsse - Chip Module lead resistance, terminals - chip	T _C = 25°C, pro Schalter / per switch	R _{CC+EE'}		1,10	mΩ
Lagertemperatur Storage temperature		T _{stg}	-40		125 °C
Anzugsdrehmoment f. Modulmontage Mounting torque for modul mounting	Schraube M5 - Montage gem. gültiger Applikationsschrift Screw M5 - Mounting according to valid application note	M	3,00		6,00 Nm
Anzugsdrehmoment f. elektr. Anschlüsse Terminal connection torque	Schraube M6 - Montage gem. gültiger Applikationsschrift Screw M6 - Mounting according to valid application note	M	3,0	-	6,0 Nm
Gewicht Weight		G		345	g

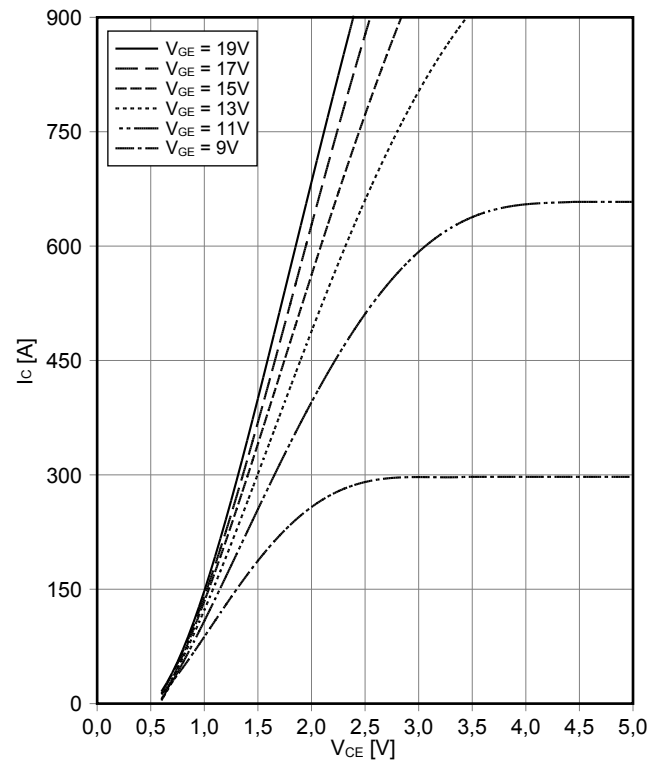
Ausgangskennlinie IGBT, Wechselrichter (typisch)
output characteristic IGBT, Inverter (typical)

$I_C = f(V_{CE})$
 $V_{GE} = 15\text{ V}$



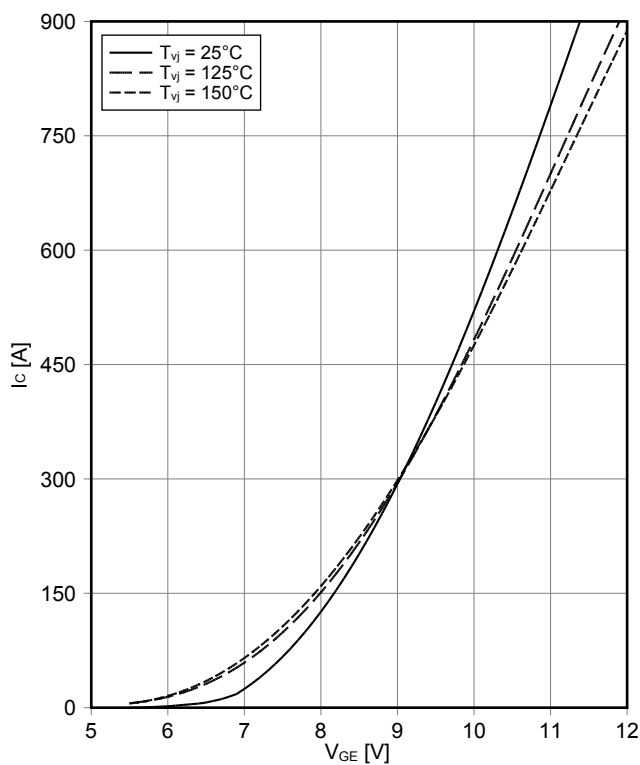
Ausgangskennlinienfeld IGBT, Wechselrichter (typisch)
output characteristic IGBT, Inverter (typical)

$I_C = f(V_{CE})$
 $T_{vj} = 150^\circ\text{C}$



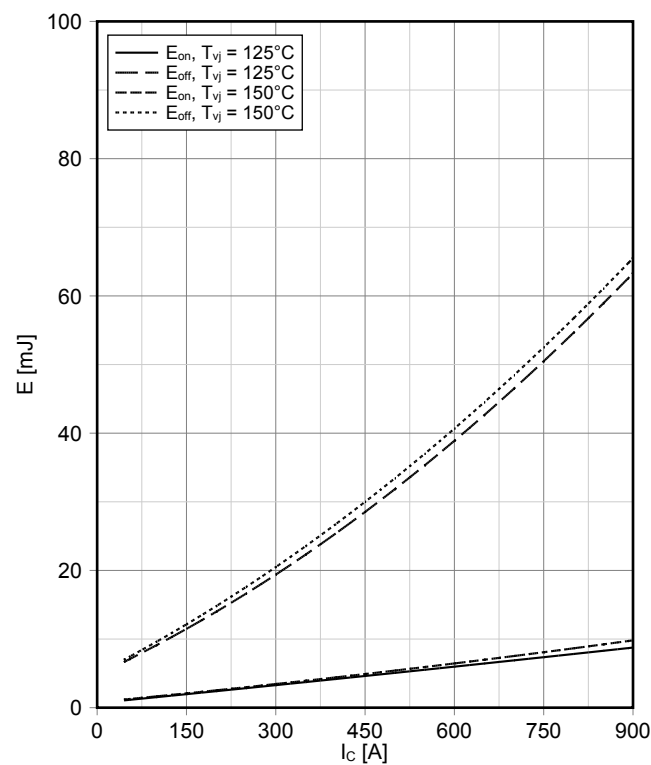
Übertragungscharakteristik IGBT, Wechselrichter (typisch)
transfer characteristic IGBT, Inverter (typical)

$I_C = f(V_{GE})$
 $V_{CE} = 20\text{ V}$



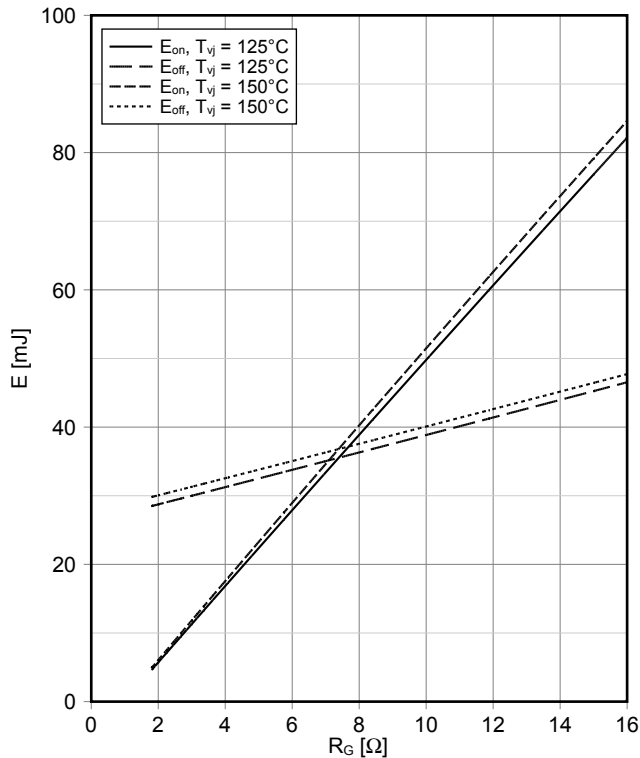
Schaltverluste IGBT, Wechselrichter (typisch)
switching losses IGBT, Inverter (typical)

$E_{on} = f(I_C)$, $E_{off} = f(I_C)$
 $V_{GE} = \pm 15\text{ V}$, $R_{Gon} = 1.8\ \Omega$, $R_{Goff} = 1.8\ \Omega$, $V_{CE} = 300\text{ V}$



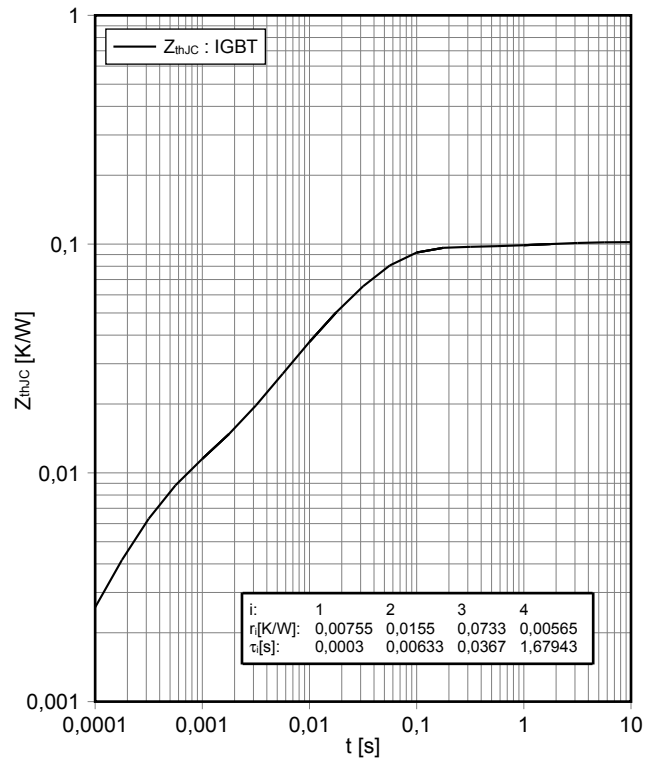
Schaltverluste IGBT, Wechselrichter (typisch) switching losses IGBT, Inverter (typical)

$E_{on} = f(R_G)$, $E_{off} = f(R_G)$
 $V_{GE} = \pm 15\text{ V}$, $I_C = 450\text{ A}$, $V_{CE} = 300\text{ V}$



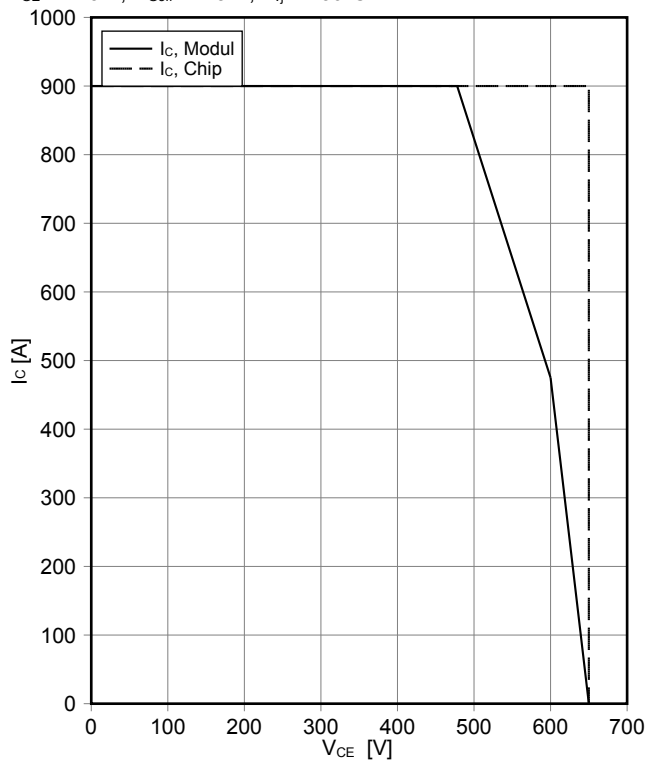
Transienter Wärmewiderstand IGBT, Wechselrichter transient thermal impedance IGBT, Inverter

$Z_{thJC} = f(t)$



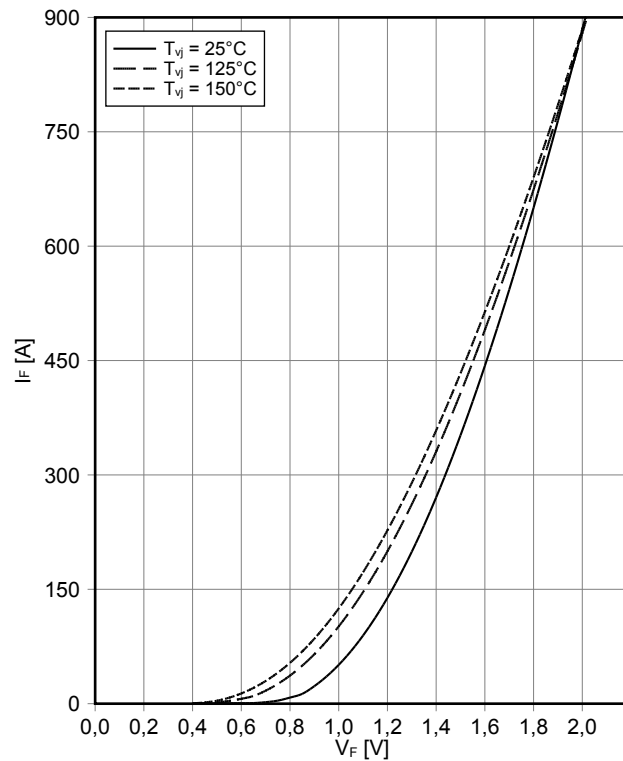
Sicherer Rückwärts-Arbeitsbereich IGBT, Wechselrichter (RBSOA) reverse bias safe operating area IGBT, Inverter (RBSOA)

$I_C = f(V_{CE})$
 $V_{GE} = \pm 15\text{ V}$, $R_{Goff} = 1.8\ \Omega$, $T_{vj} = 150^\circ\text{C}$



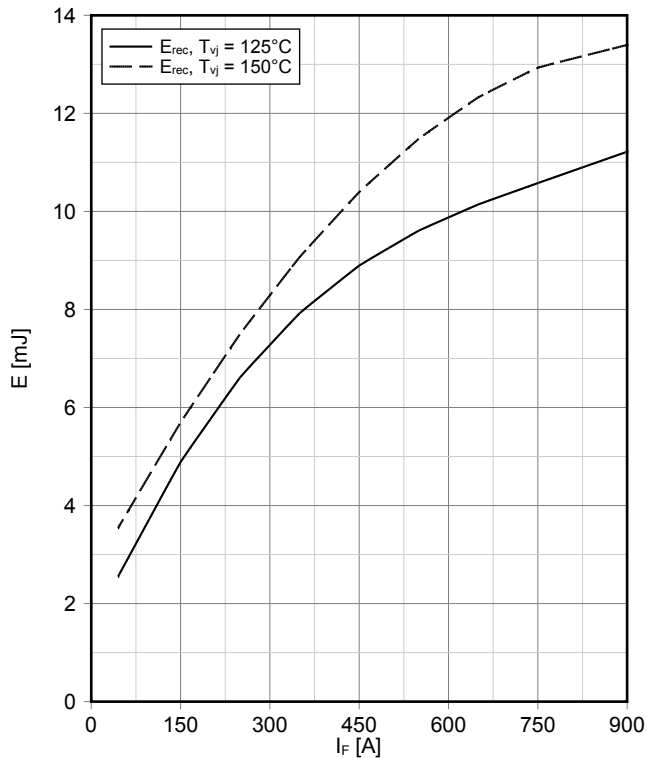
Durchlasskennlinie der Diode, Wechselrichter (typisch) forward characteristic of Diode, Inverter (typical)

$I_F = f(V_F)$



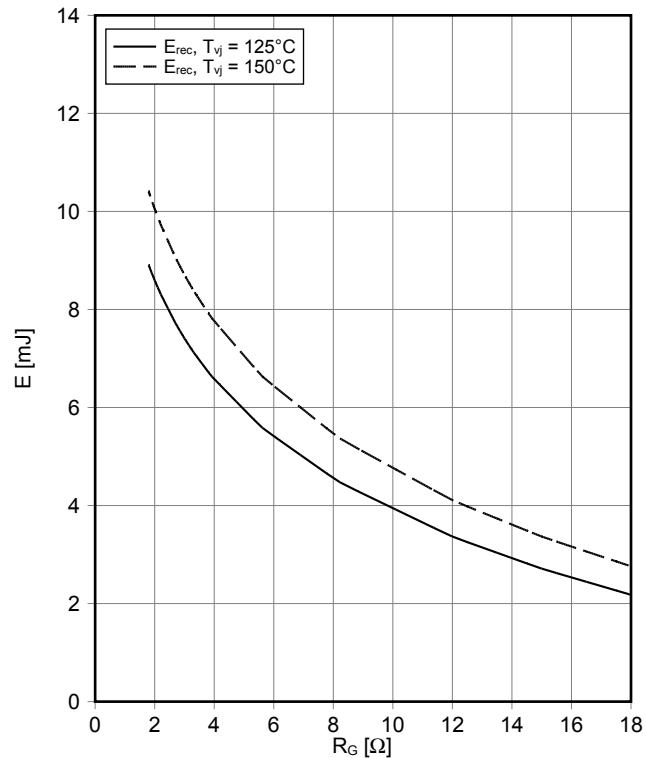
Schaltverluste Diode, Wechselrichter (typisch)
switching losses Diode, Inverter (typical)

$E_{rec} = f(I_F)$
 $R_{Gon} = 1.8 \Omega, V_{CE} = 300 V$



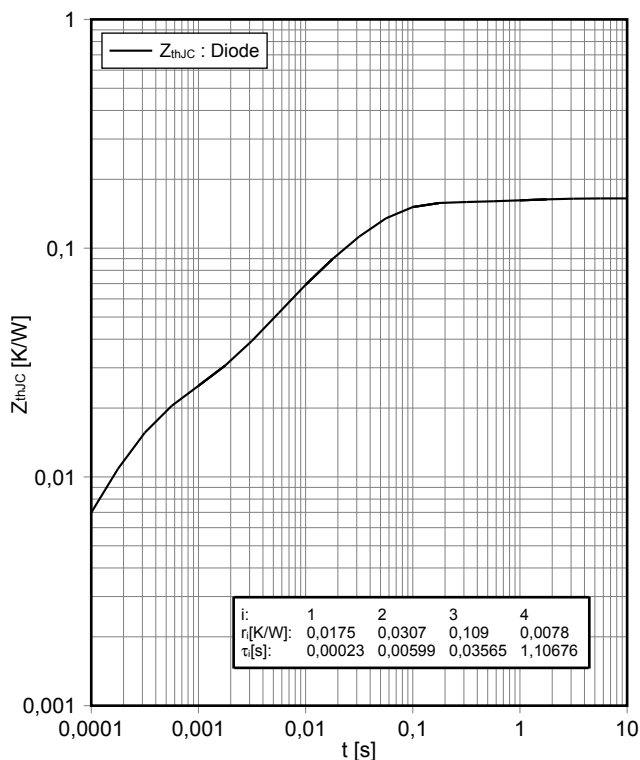
Schaltverluste Diode, Wechselrichter (typisch)
switching losses Diode, Inverter (typical)

$E_{rec} = f(R_G)$
 $I_F = 450 A, V_{CE} = 300 V$



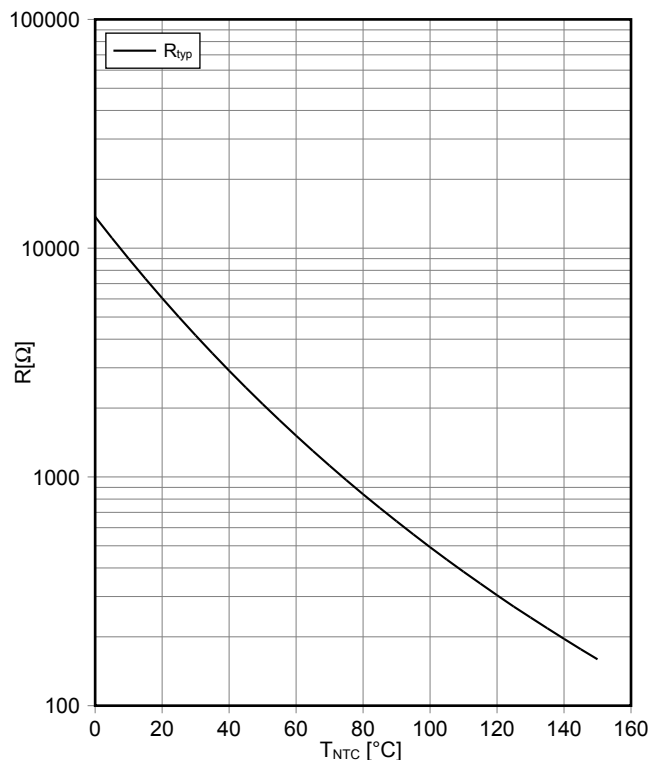
Transienter Wärmewiderstand Diode, Wechselrichter
transient thermal impedance Diode, Inverter

$Z_{thJC} = f(t)$

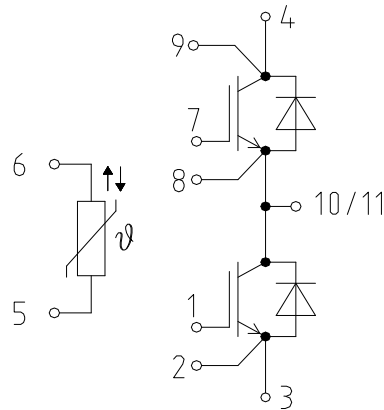


NTC-Widerstand-Temperaturkennlinie (typisch)
NTC-Thermistor-temperature characteristic (typical)

$R = f(T)$



Schaltplan / Circuit diagram



Gehäuseabmessungen / Package outlines

